



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-02-26
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MQYG*UA65AA5	A	Z6HA	2014-02-26
Amount	UoM	Unit type	ST ECOPACK Grade	
24.526	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3X3X0.95	6	No lead	
Comment	Package: VDFPN 6 3X3 0,95 PITCH			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MQYG*UA65AAS					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.792	mg	SUPPLIER	Silicon die	Si	7440-21-3		0.779	mg	983586	31762
Silicon die			mg	supplier	Back metallization	Gold (Au)	7440-57-5		0.002	mg	2525	82
Silicon die			mg	supplier	Back metallization	Nickel (Ni)	7440-02-0		0.005	mg	6313	204
Silicon die			mg	supplier	Passivation	Gamma-butyrolactone	96-48-0		0.004	mg	5051	163
Silicon die			mg	SUPPLIER	Passivation	Polyhydroxyamide	55295-98-2		0.002	mg	2525	82
Leadframe	Copper & its alloys	8.861	mg	SUPPLIER	Alloy	Copper (Remaining)	7440-50-8		8.558	mg	965805	348936
Leadframe			mg	SUPPLIER	Alloy	Iron (2.1~2.6%)	7439-89-6		0.2	mg	22571	8155
Leadframe			mg	SUPPLIER	Alloy	Lead (0.01max)	7439-92-1		0.001	mg	113	41
Leadframe			mg	SUPPLIER	Alloy	Phosphorus (0.015~0.15%)	7723-14-0		0.002	mg	226	82
Leadframe			mg	SUPPLIER	Alloy	Zinc (0.05~0.20%)	7440-66-6		0.011	mg	1241	449
Leadframe			mg	SUPPLIER	Alloy	Silver (0.5~1.5%)	7440-22-4		0.089	mg	10044	3629
Die attach	Other organic materials	0.095	mg	SUPPLIER	Epoxy	Silver (80 - 100%)	7440-22-4		0.076	mg	800000	3099
Die attach			mg	SUPPLIER	Epoxy	Carbocyclic Acrylates (10 -30%)	proprietary		0.009	mg	94737	367
Die attach			mg	SUPPLIER	Epoxy	Bismaleimide resin (1-10%)	proprietary		0.003	mg	31579	122
Die attach			mg	SUPPLIER	Epoxy	2-preponic acid, 2-methyl (1-10%)	68586-19-6		0.003	mg	31579	122
Die attach			mg	SUPPLIER	Epoxy	Additive (1-10%)	proprietary		0.003	mg	31579	122
Die attach			mg	SUPPLIER	Epoxy	Dicumyl peroxide (0.1 - 1.0)	80-43-3		0.001	mg	10526	41
Bonding wire	Other inorganic materials	0.088	mg	SUPPLIER	Bonding Wire	Au	7440-57-5		0.088	mg	1000000	3588
Encapsulation	Other organic materials	14.485	mg	SUPPLIER	molding compound	Silica Fused (85~95%)	60676-86-0		13.573	mg	937038	553413
Encapsulation			mg	SUPPLIER	molding compound	Epoxy Resin (1~5%)	Proprietary		0.434	mg	29962	17696
Encapsulation			mg	SUPPLIER	molding compound	Phenol Resin (1~5%)	Proprietary		0.435	mg	30031	17736
Encapsulation			mg	SUPPLIER	molding compound	Carbon Black (0.1~0.5%)	1333-86-4		0.043	mg	2969	1753
Finishing	Other inorganic materials	0.205	mg	SUPPLIER	Connection coating	Sn	7440-31-5		0.205	mg	1000000	8358